



Advanced Imaging in Orthopedic Biomechanics

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Message from the Guest Editors

Dear Colleagues,

Recent advancements in medical imaging, such as weight-bearing and dual-energy computer tomography, 3-5 Tesla magnetic resonance devices, and elastography, produce high-resolution visualization, high speed of acquisition under functional conditions, reduced radiation, and decreased cost. These and other, similar factors have made advanced imaging techniques not only popular as clinical diagnostic tools but also an integral part of many orthopedic biomechanics research studies. Numerous examples of this exist, including image-based personalized surgical planning, development of high-fidelity computer models, computer-aided surgery, personalized implant design and development, functional-imaging-based diagnosis, biomechanics-inspired advanced imaging techniques, and advanced 3D printing applications. You are invited to contribute original research papers, methodological advances, mini-reviews, and perspective articles. Articles on both advanced imaging in orthopedic biomechanics or innovative applications of conventional imaging methods in orthopedic biomechanics are welcomed.





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Message from the Editor-in-Chief

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